

Title (en)
OBJECT INSPECTION AND/OR MODIFICATION SYSTEM AND METHOD

Title (de)
VORRICHTUNG ZUR KONTROLLIE UND/ODER VERÄNDERUNG VON GEGENSTÄNDEN.

Title (fr)
SYSTEME ET PROCEDE DE CONTROLE ET/OU DE MODIFICATION D'OBJETS

Publication
EP 1012584 A4 20061004 (EN)

Application
EP 98904705 A 19980121

Priority
• US 9801528 W 19980121
• US 78662397 A 19970121
• US 82795397 A 19970406

Abstract (en)
[origin: WO9834092A2] A system and method for measuring, analysis, removal, addition or imaging of material using nanostructures in conjunction with mechanical, electromagnetic (optical) and electrical means. Techniques for fabricating such nanostructures and techniques for combining these elements in a system which can modify bulk or large area objects such as silicon wafers, and masks for lithography.

IPC 8 full level
G01N 27/00 (2006.01); **G01B 7/34** (2006.01); **G01Q 10/00** (2010.01); **G01Q 30/02** (2010.01); **G01Q 30/16** (2010.01); **G01Q 40/00** (2010.01); **G01Q 40/02** (2010.01); **G01Q 60/06** (2010.01); **G01Q 60/10** (2010.01); **G01Q 60/18** (2010.01); **G01Q 60/24** (2010.01); **G01Q 70/02** (2010.01); **G01Q 70/08** (2010.01); **G01Q 70/16** (2010.01); **G01Q 80/00** (2010.01); **G03F 1/00** (2012.01); **G03F 7/20** (2006.01); **G11B 5/23** (2006.01); **G11B 5/31** (2006.01)

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G01Q 30/02 (2013.01); **G01Q 30/16** (2013.01); **G01Q 40/00** (2013.01); **G01Q 40/02** (2013.01); **G01Q 60/06** (2013.01); **G01Q 70/02** (2013.01); **G01Q 70/06** (2013.01); **G01Q 70/16** (2013.01); **G03F 1/84** (2013.01); **G03F 7/2049** (2013.01); **G03F 7/704** (2013.01); **G03F 7/70616** (2013.01); **G01Q 80/00** (2013.01); **G11B 5/232** (2013.01); **G11B 5/3116** (2013.01); **G11B 5/3163** (2013.01); **G11B 5/3166** (2013.01)

Citation (search report)
• [XAY] US 5227626 A 19930713 - OKADA TAKAO [JP], et al
• [YA] EP 0376045 A2 19900704 - HITACHI LTD [JP]
• [Y] EP 0720050 A2 19960703 - SIEMENS AG [DE]
• [YA] US 5489339 A 19960206 - HATTORI TAKEO [JP], et al
• [XA] EP 0427443 A2 19910515 - IBM [US]
• [XA] US 5416331 A 19950516 - ICHIKAWA MASAKAZU [JP], et al
• [Y] "IN SITU SHARPENING OF ATOMIC FORCE MICROSCOPE TIPS", IBM TECHNICAL DISCLOSURE BULLETIN, IBM CORP. NEW YORK, US, vol. 38, no. 2, 1 February 1995 (1995-02-01), pages 637, XP000502713, ISSN: 0018-8689
• See references of WO 9834092A2

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US 9801528 W 19980121; AU 6250898 A 19980121; EP 98904705 A 19980121